NSM11156DW6T1G

Dual PNP Transistors

General Purpose PNP Transistor and PNP Transistor with Monolithic Bias Network

NSM11156DW6T1G contains a single PNP transistor and a monolithic bias network PNP transistor with two resistors; a series base resistor and a base–emitter resistor. This device is designed to replace multiple transistors and resistors on customer boards by integrating these components into a single device. NSM11156DW6T1G is housed in a SC–88/SOT–363 package which is ideal for low power surface mount applications in space constrained applications.

Features

- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- Q1: PNP BRT, R1 = R2 = 10 k
- Q2: PNP
- This is a Pb–Free Device

Applications

- Logic Switching
- Amplification
- Driver Circuits
- Interface Circuits

MAXIMUM RATINGS

(T_A = 25°C unless otherwise noted)

Rating – Q1 (PNP BRT)	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	–50	Vdc
Collector-Emitter Voltage	V_{CEO}	–50	Vdc
Collector Current	I_C	–100	mAdc
Rating – Q2 (PNP)	**Symbol**	**Value**	**Unit**
Collector – Base Voltage	$V_{(BR)CBO}$	–80	Vdc
Collector – Emitter Voltage	$V_{(BR)CEO}$	–65	Vdc
Emitter – Base Voltage	$V_{(BR)EBO}$	–5.0	Vdc
Collector Current – Continuous	I_C	–100	mAdc

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

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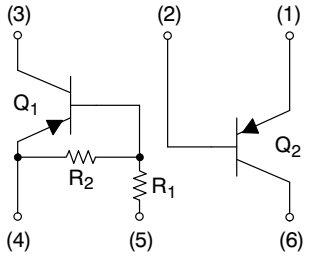
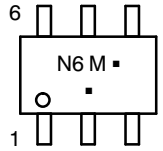


1

SC–88/SOT–363
CASE 419B
STYLE 1

MARKING DIAGRAM



N6 = Device Code
M = Date Code*
▪ = Pb–Free Package
(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping†
NSM11156DW6T1G	SC–88 (Pb–Free)	3000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

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March, 2008 – Rev. 0

Publication Order Number:
NSM11156DW6/D

THERMAL CHARACTERISTICS

Characteristic (One Junction Heated)	Symbol	Max	Unit
Total Device Dissipation T_A = 25°C Derate above 25°C	P_D	 180 (Note 1) 1.44 (Note 1)	 mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	692 (Note 1)	°C/W
Characteristic (Both Junctions Heated)	**Symbol**	**Max**	**Unit**
Total Device Dissipation, T_A = 25°C Derate above 25°C	P_D	 230 1.83	 mW mW/°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	544	°C/W
Junction and Storage Temperature	T_J, T_{stg}	−55 to +150	°C

1. FR−4 @ Minimum Pad of 1.45 mm^2, 1 oz Cu.

ELECTRICAL CHARACTERISTICS − Q1 (PNP BRT) (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Collector-Base Cutoff Current (V_{CB} = −50 V, I_E = 0)	I_{CBO}	−	−	−100	nAdc
Collector-Emitter Cutoff Current (V_{CE} = −50 V, I_B = 0)	I_{CEO}	−	−	−500	nAdc
Emitter-Base Cutoff Current (V_{EB} = −6.0 V, I_C = 0)	I_{EBO}	−	−	−0.5	mAdc
Collector-Base Breakdown Voltage (I_C = −10 μA, I_E = 0)	$V_{(BR)CBO}$	−50	−	−	Vdc
Collector-Emitter Breakdown Voltage (Note 2) (I_C = −2.0 mA, I_B = 0)	$V_{(BR)CEO}$	−50	−	−	Vdc
ON CHARACTERISTICS (Note 2)					
DC Current Gain (V_{CE} = −10 V, I_C = −5.0 mA)	h_{FE}	35	60	−	
Collector-Emitter Saturation Voltage (I_C = −10 mA, I_B = −0.3 mA)	$V_{CE(sat)}$	−	−	−0.25	Vdc
Output Voltage (on) (V_{CC} = −5.0 V, V_B = −2.5 V, R_L = 1.0 kΩ)	V_{OL}	−	−	−0.2	Vdc
Output Voltage (off) (V_{CC} = −5.0 V, V_B = −0.5 V, R_L = 1.0 kΩ)	V_{OH}	−4.9	−	−	Vdc
Input Resistor	R1	7.0	10	13	kΩ
Resistor Ratio	R1/R2	0.8	1.0	1.2	

2. Pulse Test: Pulse Width < 300 μs, Duty Cycle < 2.0%

ELECTRICAL CHARACTERISTICS – Q2 (PNP) (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
OFF CHARACTERISTICS					
Collector – Emitter Breakdown Voltage (I_C = −10 mA)	$V_{(BR)CEO}$	−65	–	–	V
Collector – Emitter Breakdown Voltage (I_C = −10 μA, V_{EB} = 0)	$V_{(BR)CES}$	−80	–	–	V
Collector – Base Breakdown Voltage (I_C = −10 μA)	$V_{(BR)CBO}$	−80	–	–	V
Emitter – Base Breakdown Voltage (I_E = −1.0 μA)	$V_{(BR)EBO}$	−5.0	–	–	V
Collector Cutoff Current (V_{CB} = −30 V) (V_{CB} = −30 V, T_A = 150°C)	I_{CBO}	– –	– –	−15 −4.0	nA μA
ON CHARACTERISTICS					
DC Current Gain (I_C = −10 μA, V_{CE} = −5.0 V) (I_C = −2.0 mA, V_{CE} = −5.0 V)	h_{FE}	– 220	150 290	– 475	–
Collector – Emitter Saturation Voltage (I_C = −10 mA, I_B = −0.5 mA) (I_C = −100 mA, I_B = −5.0 mA)	$V_{CE(sat)}$	– –	– –	−0.3 −0.65	V
Base – Emitter Saturation Voltage (I_C = −10 mA, I_B = −0.5 mA) (I_C = −100 mA, I_B = −5.0 mA)	$V_{BE(sat)}$	– –	−0.7 −0.9	– –	V
Base – Emitter On Voltage (I_C = −2.0 mA, V_{CE} = −5.0 V) (I_C = −10 mA, V_{CE} = −5.0 V)	$V_{BE(on)}$	−0.6 –	– –	−0.75 −0.82	V

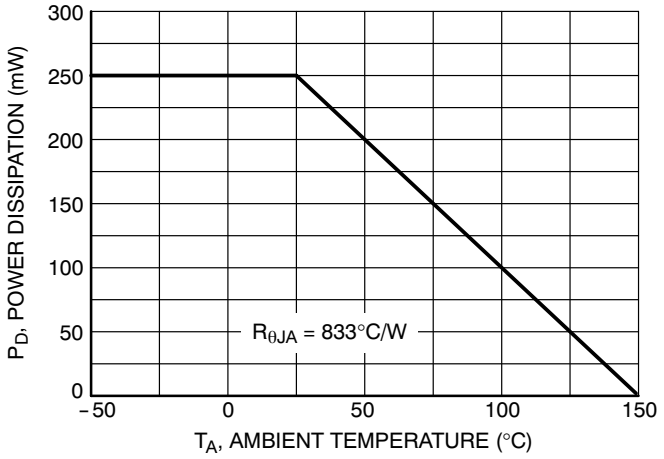
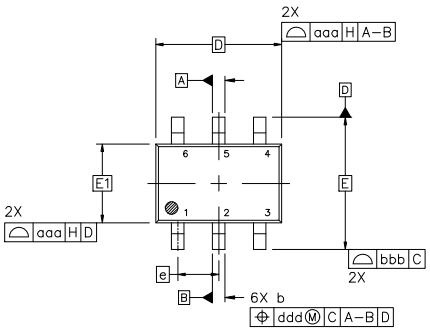


Figure 1. Derating Curve

SC−88 2.00x1.25x0.90, 0.65P
CASE 419B−02
ISSUE Z

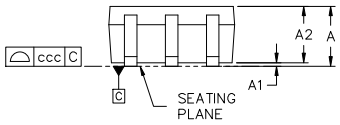
DATE 18 APR 2024



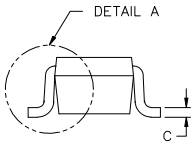
TOP VIEW

NOTES:

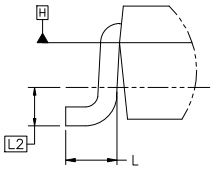
1. DIMENSIONING AND TOLERANCING CONFORM TO ASME Y14.5−2018.
2. ALL DIMENSION ARE IN MILLIMETERS.
3. DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER END.
4. DIMENSIONS D AND E1 AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY AND DATUM H.
5. DATUMS A AND B ARE DETERMINED AT DATUM H.
6. DIMENSIONS b AND c APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.08 AND 0.15 FROM THE TIP.
7. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF DIMENSION b AT MAXIMUM MATERIAL CONDITION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT.



SIDE VIEW

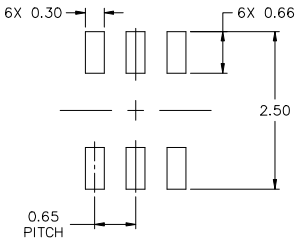


END VIEW



DETAIL A
SCALE 2:1

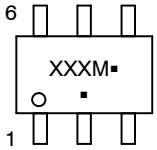
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	−−−	−−−	1.10
A1	0.00	−−−	0.10
A2	0.70	0.90	1.00
b	0.15	0.20	0.25
c	0.08	0.15	0.22
D	2.00 BSC		
E	2.10 BSC		
E1	1.25 BSC		
e	0.65 BSC		
L	0.26	0.36	0.46
L2	0.15 BSC		
aaa	0.15		
bbb	0.30		
ccc	0.10		
ddd	0.10		



RECOMMENDED MOUNTING FOOTPRINT*

* FOR ADDITIONAL INFORMATION ON OUR Pb−FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ONSEMI SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
M = Date Code*
▪ = Pb−Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

STYLES ON PAGE 2

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DESCRIPTION:	SC−88 2.00x1.25x0.90, 0.65P	PAGE 1 OF 2

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CASE 419B−02
ISSUE Z

DATE 18 APR 2024

STYLE 1:
PIN 1. EMITTER 2
2. BASE 2
3. COLLECTOR 1
4. EMITTER 1
5. BASE 1
6. COLLECTOR 2

STYLE 2:
CANCELLED

STYLE 3:
CANCELLED

STYLE 4:
PIN 1. CATHODE
2. CATHODE
3. COLLECTOR
4. EMITTER
5. BASE
6. ANODE

STYLE 5:
PIN 1. ANODE
2. ANODE
3. COLLECTOR
4. EMITTER
5. BASE
6. CATHODE

STYLE 6:
PIN 1. ANODE 2
2. N/C
3. CATHODE 1
4. ANODE 1
5. N/C
6. CATHODE 2

STYLE 7:
PIN 1. SOURCE 2
2. DRAIN 2
3. GATE 1
4. SOURCE 1
5. DRAIN 1
6. GATE 2

STYLE 8:
CANCELLED

STYLE 9:
PIN 1. EMITTER 2
2. EMITTER 1
3. COLLECTOR 1
4. BASE 1
5. BASE 2
6. COLLECTOR 2

STYLE 10:
PIN 1. SOURCE 2
2. SOURCE 1
3. GATE 1
4. DRAIN 1
5. DRAIN 2
6. GATE 2

STYLE 11:
PIN 1. CATHODE 2
2. CATHODE 2
3. ANODE 1
4. CATHODE 1
5. CATHODE 1
6. ANODE 2

STYLE 12:
PIN 1. ANODE 2
2. ANODE 2
3. CATHODE 1
4. ANODE 1
5. ANODE 1
6. CATHODE 2

STYLE 13:
PIN 1. ANODE
2. N/C
3. COLLECTOR
4. EMITTER
5. BASE
6. CATHODE

STYLE 14:
PIN 1. VREF
2. GND
3. GND
4. IOUT
5. VEN
6. VCC

STYLE 15:
PIN 1. ANODE 1
2. ANODE 2
3. ANODE 3
4. CATHODE 3
5. CATHODE 2
6. CATHODE 1

STYLE 16:
PIN 1. BASE 1
2. EMITTER 2
3. COLLECTOR 2
4. BASE 2
5. EMITTER 1
6. COLLECTOR 1

STYLE 17:
PIN 1. BASE 1
2. EMITTER 1
3. COLLECTOR 2
4. BASE 2
5. EMITTER 2
6. COLLECTOR 1

STYLE 18:
PIN 1. VIN1
2. VCC
3. VOUT2
4. VIN2
5. GND
6. VOUT1

STYLE 19:
PIN 1. I OUT
2. GND
3. GND
4. V CC
5. V EN
6. V REF

STYLE 20:
PIN 1. COLLECTOR
2. COLLECTOR
3. BASE
4. EMITTER
5. COLLECTOR
6. COLLECTOR

STYLE 21:
PIN 1. ANODE 1
2. N/C
3. ANODE 2
4. CATHODE 2
5. N/C
6. CATHODE 1

STYLE 22:
PIN 1. D1 (i)
2. GND
3. D2 (i)
4. D2 (c)
5. VBUS
6. D1 (c)

STYLE 23:
PIN 1. Vn
2. CH1
3. Vp
4. N/C
5. CH2
6. N/C

STYLE 24:
PIN 1. CATHODE
2. ANODE
3. CATHODE
4. CATHODE
5. CATHODE
6. CATHODE

STYLE 25:
PIN 1. BASE 1
2. CATHODE
3. COLLECTOR 2
4. BASE 2
5. EMITTER
6. COLLECTOR 1

STYLE 26:
PIN 1. SOURCE 1
2. GATE 1
3. DRAIN 2
4. SOURCE 2
5. GATE 2
6. DRAIN 1

STYLE 27:
PIN 1. BASE 2
2. BASE 1
3. COLLECTOR 1
4. EMITTER 1
5. EMITTER 2
6. COLLECTOR 2

STYLE 28:
PIN 1. DRAIN
2. DRAIN
3. GATE
4. SOURCE
5. DRAIN
6. DRAIN

STYLE 29:
PIN 1. ANODE
2. ANODE
3. COLLECTOR
4. EMITTER
5. BASE/ANODE
6. CATHODE

STYLE 30:
PIN 1. SOURCE 1
2. DRAIN 2
3. DRAIN 2
4. SOURCE 2
5. GATE 1
6. DRAIN 1

Note: Please refer to datasheet for style callout. If style type is not called out in the datasheet refer to the device datasheet pinout or pin assignment.

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